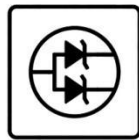


MSKSEMI

SEMICONDUCTOR



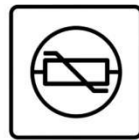
ESD



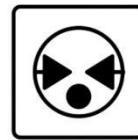
TVS



TSS



MOV



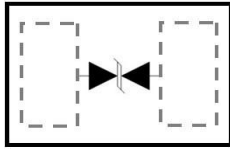
GDT



PLED

Product data sheet

PIN CONFIGURATION



DFN1006

Features

- Capacitance: 15pF(typ.)
- Reverse Working Voltage: 5V
- IEC 61000-4-2 (ESD Air): ±25KV
- IEC 61000-4-2 (ESD Contact): ±25KV
- IEC 61000-4-5 (Lightning 8/20µs): 8A

Applications

- Smart Phone and Tablet PC
- TV and Set Top Box
- Wearable Devices
- PDA

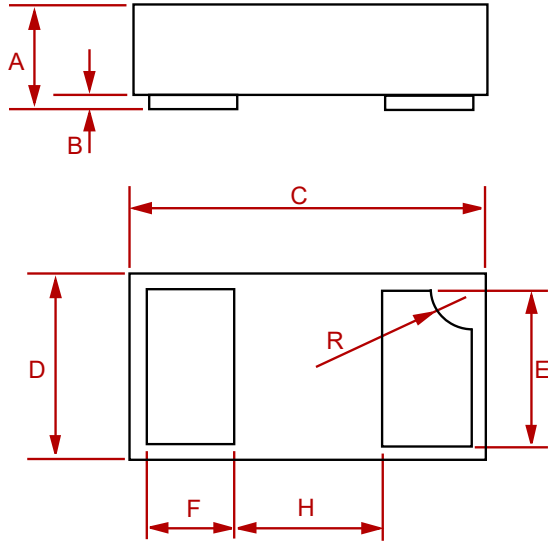
Limiting Values(T_A = 25 °C, unless otherwise specified)

Symbol	Parameter	Conditions	Min	Max	Unit
V _{ESD}	Electrostatic Discharge Voltage	IEC 61000-4-2; Contact Discharge	-	±25	kV
		IEC 61000-4-2; Air Discharge	-	±25	kV
P _{PP}	Peak Pulse Power	t _p = 8/20 µs	-	80	W
I _{PPM}	Rated Peak Pulse Current	t _p = 8/20 µs	-	8	A
T _A	Ambient Temperature Range	-	-55	125	°C
T _{stg}	Storage Temperature Range	-	-55	150	°C

Electrical Characteristics(T_A = 25 °C, unless otherwise specified)

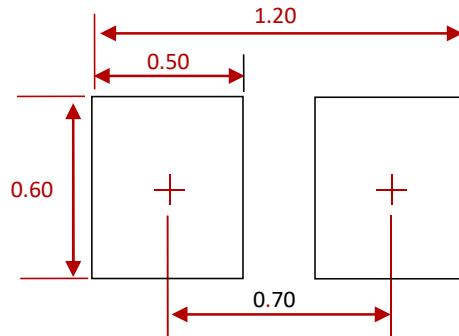
Symbol	Parameter	Conditions	Min	Typ.	Max	Unit
V _{RWM}	Reverse Working Voltage	T _A = 25 °C	-	-	5.0	V
V _{BR}	Breakdown Voltage	I _R = 1mA; T _A = 25 °C	5.6	6.5	8.4	V
I _R	Reverse Leakage Current	V _{RWM} = 5V; T _A = 25 °C	-	-	0.1	µA
V _C	Clamping Voltage	I _{PP} =1A, t _p =8/20µs	-	-	6	V
		I _{PP} =8A, t _p =8/20µs	-	-	10	V
C _J	Junction Capacitance	V _R = 0V, f = 1 MHz	-	15	18	pF

PACKAGE MECHANICAL DATA



Dim	Inches		Millimeters	
	MIN	MAX	MIN	MAX
A	0.0125	0.02	0.32	0.52
B	0.000	0.002	0.00	0.05
C	0.037	0.043	0.95	1.080
D	0.022	0.027	0.55	0.680
E	0.016	0.024	0.40	0.60
F	0.008	0.012	0.20	0.30
H	0.015Typ.		0.40Typ.	
R	0.001	0.005	0.05	0.15

Suggested Pad Layout



NOTES:

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.

REEL SPECIFICATION

P/N	PKG	QTY
PESDNC2FD5VB-MS	DFN1006	10000

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